CLAIMS

[CLAIM 1] A sheet-like thermally curable composition comprising a phenolic resin, an inorganic filler, and silicone-type particles, wherein the silicone-type particles have an epoxy group.

[CLAIM 2] The thermally curable composition according to claim 1 further comprising an epoxy resin.

[CLAIM 3] The thermally curable composition according to claim 1 or 2 wherein, taking a first weight which is a weight of the thermally curable composition less a total weight of the inorganic filler to be 100%, a total weight of the silicone-type particles is 0.5% to 50%.

[CLAIM 4] The thermally curable composition according to any of claims 1 through 3 wherein minimum melt viscosity is 100 Pa·s to 10000 Pa·s.

[CLAIM 5] The thermally curable composition according to any of claims 1 through 4 which is for sealing an electronic component.

[CLAIM 6] A sheet comprising the thermally curable composition according to any of claims 1 through 5, and further comprising,

where two faces of the thermally curable composition are defined such that there is a first face and a second face opposite the first face,

a first separator which is provided over the first face; and

a second separator which is provided over the second face.

[CLAIM 7] A device manufacturing method comprising:

an operation in which the thermally curable composition according to any of claims 1 through 5 is arranged over an electronic component;

an operation in which a composite body is formed which comprises the electronic component and the thermally curable composition which covers the electronic component; and

an operation in which heating of the composite body causes curing of the thermally curable composition to occur;

wherein the operation in which the composite body is formed comprises a step in which softening of the thermally curable composition is made to occur.